2025-02-14(금), 15:10-17:10
좌장: 추후업데이트 예정

Q. Metrology, Inspection, Analysis, and Yield Enhancement 분과

[FH3-Q] Metrology, Inspection, Analysis, and Yield Enhancement II

초청 FH3-Q-1 15:10-15:40	A study on improving accuracy of optical 3-D profile measurement using in-wafer gradient of dimensionally reduced ellipsometry spectrum Hyeong-Jun Jeong[1], Sungyoon Ryu[1], Taejin Kim[1], Gwanghun Jung[1], Young-Seok Kim[1], Younghoon Sohn[1], and Minkyu Kim[2] [1]Metrology & Inspection Technology Team, Samsung Electronics, [2]CSE Team, Samsung Electronics
초청 FH3-Q-2 15:40-16:10	정용우 TL (초청연사)
초청 FH3-Q-3 16:10-16:40	Development of various EUV sources for application in actinic tools for EUV masks Dong Gun Lee ESOL (EUV Solution)
FH3-Q-4 16:40-16:55	HBM Stack Chip MI Solution Hye Yun Seong, Young Hoon Lee, and Sung Hyun Yoon SK hynix
FH3-Q-5 16:55-17:10	The Industry's First Study on Inline Mass Measurement Methods for Chip-Level Warpage to Yield Improvement of HBM Sang-Yeop Lee[1], Sang yup Lee[2], In Tae Whoang[1], Jung Hwi Kim[1], Min Yeop Lee[1], and Young Hoon Lee[1] [1]SK Hynix, [2]Georgia Institute of Technology